

# **HSC277**

Silicon Epitaxial Planar Diode for UHF/VHF tuner Band Switch

REJ03G0585-0200 (Previous: ADE-208-413A) Rev.2.00 Mar 29, 2005

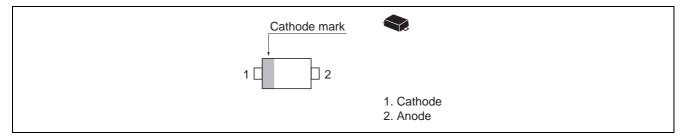
### Features

- Low forward resistance. ( $r_f = 0.7 \Omega max$ )
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

### **Ordering Information**

Type No.	Cathode Mark	Package Name	Package Code (Previous Code)
HSC277	Laser	UFP	PWSF0002ZA-A (UFP)

### **Pin Arrangement**





# Absolute Maximum Ratings

			(Ta = 25°C)
ltem	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	35	V
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-45 to +125	°C
Operation temperature	Topr	-20 to +60	°C

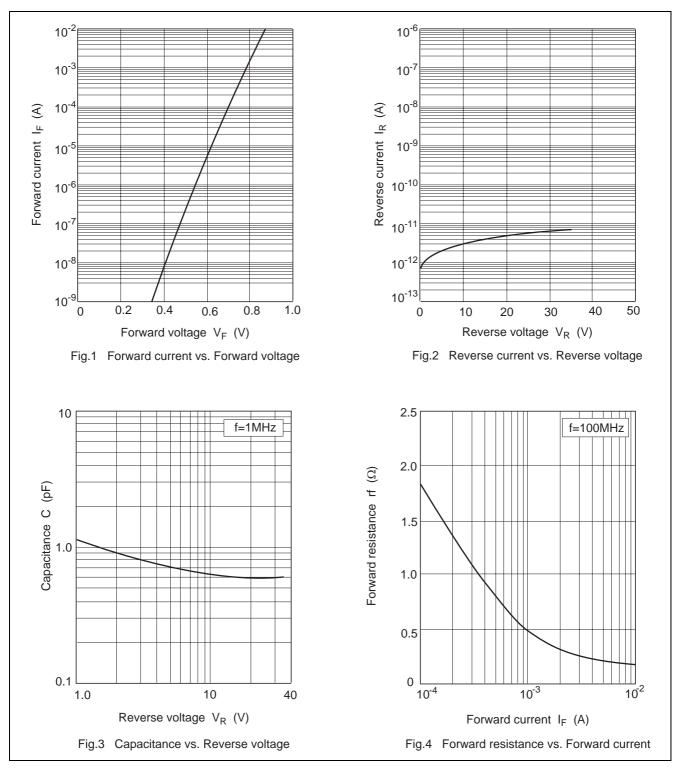
## **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse voltage	V <sub>R</sub>	35.0	—	—	V	I <sub>R</sub> = 10 μA
Forward voltage	V <sub>F</sub>	—	—	1.0	V	I <sub>F</sub> = 10 mA
Reverse current	I <sub>R</sub>	_	—	50	nA	V <sub>R</sub> = 25 V
Capacitance	С	_	—	1.2	pF	$V_R = 6 V, f = 1 MHz$
Forward resistance	r <sub>f</sub>	_	—	0.7	Ω	I <sub>F</sub> = 2 mA, f = 100 MHz

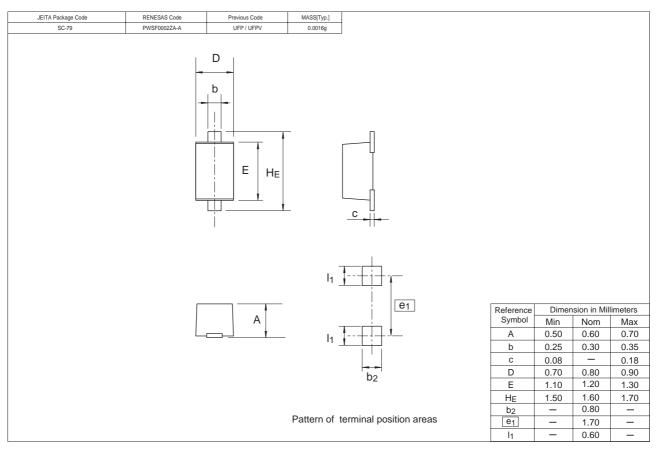


### **Main Characteristic**





### Package Dimensions





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